

## PACKAGE STRUCTURE

### ABSTRACT OF THE DISCLOSURE

A package structure includes a first encapsulation member, a second encapsulation member, at least one semiconductor chip, a plurality of metal pins and a second insulation layer. The first encapsulation member includes a first metal layer, a first insulation layer and a second metal layer. The at least one semiconductor chip is disposed between the first encapsulation member and the second encapsulation member. The at least one semiconductor chip comprises a plurality of conductive terminals connected with the first metal layer or a third metal layer. The plurality of metal pins are disposed between and extended outward from the first encapsulation member and the second encapsulation member. The second insulation layer is disposed between the first encapsulation member and the second encapsulation member for securing the first encapsulation member, the second encapsulation member, the at least one semiconductor chip, and the plurality of metal pins.

Figure 1A